

COMPLIANT

# N-Channel 150-V (D-S) 175 °C MOSFET

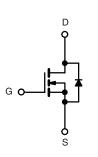
PRODUCT SUMMARY			
V <sub>DS</sub> (V)	R <sub>DS(on)</sub> (Ω)	I <sub>D</sub> (A)	
150	0.052 at V <sub>GS</sub> = 10 V	25	
	0.060 at V <sub>GS</sub> = 6 V	23	



- TrenchFET<sup>®</sup> Power MOSFET
- 175 °C Junction Temperature
- PWM Optimized
- 100 % Rg Tested
- Compliant to RoHS Directive 2002/95/EC

#### **APPLICATIONS**

• Primary Side Switch



N-Channel MOSFET

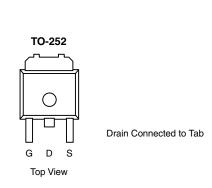
<b>ABSOLUTE MAXIMUM RATINGS</b> $T_A = 25 \text{ °C}$ , unless otherwise noted				
Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V <sub>DS</sub>	150	v	
Gate-Source Voltage	V <sub>GS</sub>	± 20	v	
Continuous Drain Current (T <sub>J</sub> = 175 °C) <sup>b</sup>	T <sub>C</sub> = 25 °C	1-	25	
	T <sub>C</sub> = 125 °C	, I <sub>D</sub>	14.5	
Pulsed Drain Current	I <sub>DM</sub>	50	A	
Continuous Source Current (Diode Conduction)	۱ <sub>S</sub>	25		
Avalanche Current	I <sub>AR</sub>	25		
Repetitive Avalanche Energy (Duty Cycle $\leq$ 1 %)	L = 0.1 mH	E <sub>AR</sub>	31	mJ
Maximum Power Dissipation	T <sub>C</sub> = 25 °C	Pn	136 <sup>b</sup>	w
Maximum Power Dissipation	T <sub>A</sub> = 25 °C	'D	3 <sup>a</sup>	vv
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 175	°C	

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
hunstion to Ampliant?	t ≤ 10 s	R <sub>thJA</sub>	15	18	°C/W
Junction-to-Ambient <sup>a</sup>	Steady State		40	50	
Junction-to-Case (Drain)		R <sub>thJC</sub>	0.85	1.1	

Notes:

a. Surface Mounted on 1" x 1" FR4 board.

b. See SOA curve for voltage derating.



Ordering Information:

SUD25N15-52-E3 (Lead (Pb)- free)

## SUD25N15-52

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Parameter	Symbol	Test Conditions	Min.	Typ. <sup>a</sup>	Max.	Unit	
Static		· · · · · · · · · · · · · · · · · · ·					
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS}$ = 0 V, I <sub>D</sub> = 250 µA	150			v	
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$	2		4	v	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
		$V_{DS} = 150 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			1		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS}$ = 150 V, $V_{GS}$ = 0 V, $T_{J}$ = 125 °C			50	μA	
		$V_{DS} = 150 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 175 ^{\circ}\text{C}$			250		
On-State Drain Current <sup>b</sup>	I <sub>D(on)</sub>	$V_{DS} = 5 V, V_{GS} = 10 V$	50			А	
		$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 5 \text{ A}$		0.042	0.052		
- · · · · · · · · · · · · · · · · · · ·	P	$V_{GS}$ = 10 V, $I_{D}$ = 5 A, $T_{J}$ = 125 °C			0.109	Ω	
Drain-Source On-State Resistance <sup>b</sup>	R <sub>DS(on)</sub>	$V_{GS}$ = 10 V, I <sub>D</sub> = 5 A, T <sub>J</sub> = 175 °C			0.145		
		$V_{GS} = 6 V, I_D = 5 A$		0.047	0.060		
Forward Transconductance <sup>b</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 25 A		40		S	
Dynamic <sup>a</sup>							
Input Capacitance	C <sub>iss</sub>			1725		pF	
Output Capacitance	C <sub>oss</sub>	V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 25 V, f = 1 MHz		216			
Reverse Transfer Capacitance	C <sub>rss</sub>			100			
Total Gate Charge <sup>c</sup>	Qg			33	40		
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	$V_{DS} = 75 \text{ V}, \text{ V}_{GS} = 10 \text{ V}, \text{ I}_{D} = 25 \text{ A}$		9		nC	
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>			12			
Gate Resistance	Rg		1		3	Ω	
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			15	25		
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD}$ = 50 V, $R_L$ = 3 $\Omega$		70	100		
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$\text{I}_\text{D}\cong$ 25 A, $\text{V}_\text{GEN}$ = 10 V, $\text{R}_\text{g}$ = 2.5 $\Omega$		25	40	ns	
Fall Time <sup>c</sup>	t <sub>f</sub>			60	90		
Source-Drain Diode Ratings and Cha	racteristics	Γ <sub>C</sub> = 25 °C			I		
Pulsed Current	I <sub>SM</sub>				50	А	
Diode Forward Voltage <sup>b</sup>	$V_{SD}$	$I_{F} = 25 \text{ A}, \text{ V}_{GS} = 0 \text{ V}$		0.9	1.5	V	
Source-Drain Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = 25 A, dl/dt = 100 A/μs		95	140	ns	

Notes:

a. Guaranteed by design, not subject to production testing.

b. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %.

c. Independent of operating temperature.

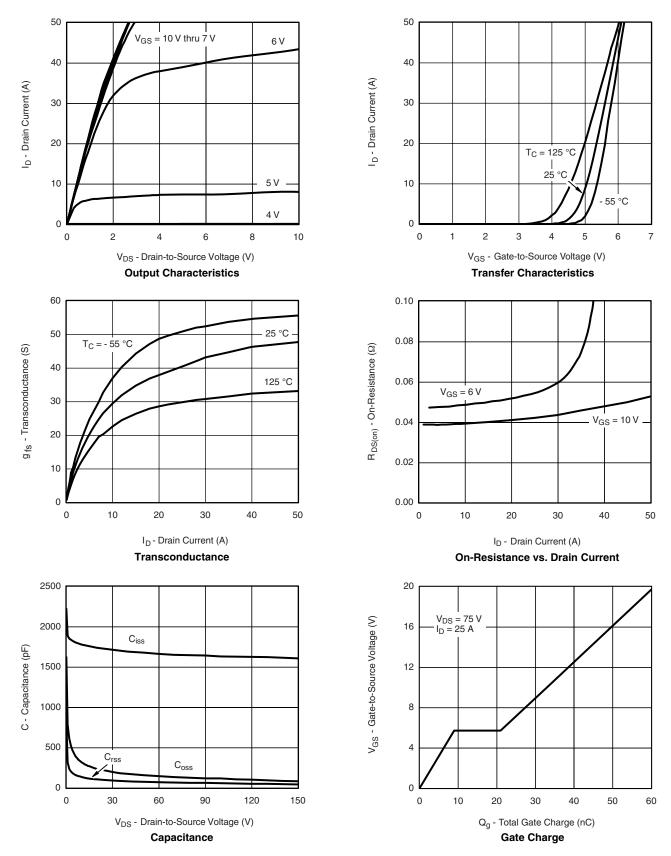
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



# SUD25N15-52

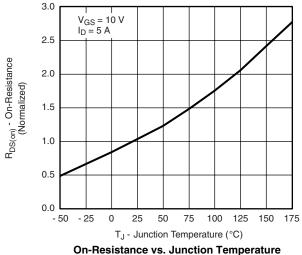
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### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

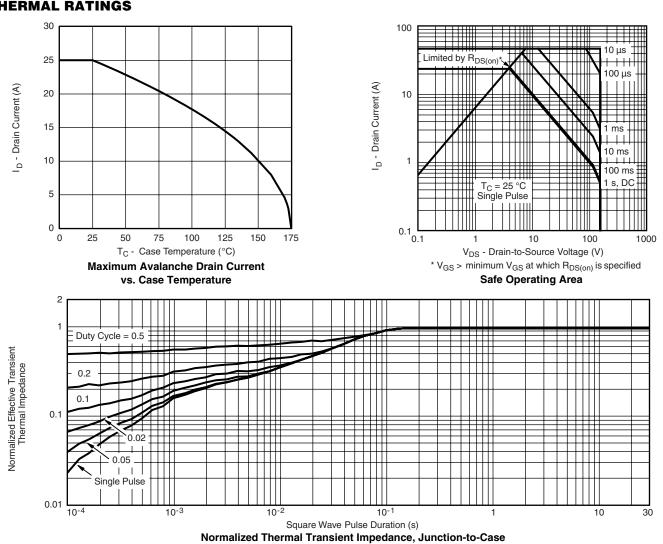


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#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted







100

10

1

0

0.3

T<sub>J</sub> = 150 °C

0.6

V<sub>SD</sub> - Source-to-Drain Voltage (V)

Source-Drain Diode Forward Voltage

I<sub>S</sub> - Source Current (A)

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T<sub>J</sub> = 25 °C

0.9

1.2

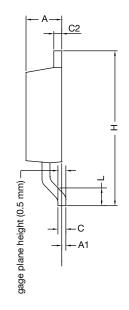


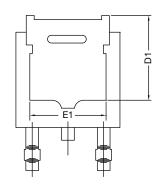


**TO-252AA Case Outline** 

#### VERSION 1: FACILITY CODE = Y







	MILLIMETERS			
DIM.	MIN.	MAX.		
А	2.18	2.38		
A1	-	0.127		
b	0.64	0.88		
b2	0.76	1.14		
b3	4.95	5.46		
С	0.46	0.61		
C2	0.46	0.89		
D	5.97	6.22		
D1	4.10	-		
E	6.35	6.73		
E1	4.32	-		
Н	9.40	10.41		
е	2.28	2.28 BSC		
e1	4.56	4.56 BSC		
L	1.40	1.78		
L3	0.89	1.27		
L4	-	1.02		
L5	1.01	1.52		

#### Note

• Dimension L3 is for reference only



#### VERSION 2: FACILITY CODE = N



	MILLIMETERS		
DIM.	MIN.	MAX.	
А	2.18	2.39	
A1	-	0.13	
b	0.65	0.89	
b1	0.64	0.79	
b2	0.76	1.13	
b3	4.95	5.46	
С	0.46	0.61	
c1	0.41	0.56	
c2	0.46	0.60	
D	5.97	6.22	
D1	5.21	-	
E	6.35	6.73	
E1	4.32	-	
e	2.29 BSC		
Н	9.94	10.34	

	MILLIMETERS		
DIM.	MIN.	MAX.	
L	1.50	1.78	
L1	2.74	l ref.	
L2	0.51 BSC		
L3	0.89	1.27	
L4	-	1.02	
L5	1.14	1.49	
L6	0.65	0.85	
θ	0°	10°	
θ1	0°	15°	
θ2	25°	35°	

#### Notes

• Dimensioning and tolerance confirm to ASME Y14.5M-1994

• All dimensions are in millimeters. Angles are in degrees

• Heat sink side flash is max. 0.8 mm

Radius on terminal is optional

ECN: E22-0399-Rev. R, 03-Oct-2022 DWG: 5347

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### **RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)**



Recommended Minimum Pads Dimensions in Inches/(mm)

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